

3x3G

Three-channel interface for up to three Gb/s serial data (or 1GbE) per channel



Features

Mezzanine board – pairs with an EDT main board (in a PCI, PCI-X, or PCIe bus), which adds high-speed DMA, programmable FPGA resources, and memory Channels O, 1, 2: Three optional SFPs (one per channel), each supporting either 1GbE (electrical or optical) or up to 3 Gb/s serial data – 850 or 1310 nm Encoding: 8b/10b (other options may be available on request) FPGA: One programmable Xilinx Virtex II Pro XC2VP7/30 DRAM: Up to 2 GB (DDR) for snapshot recording and data buffering

Description

The 3x3G is a mezzanine board that pairs with an EDT main board (for PCI or PCI Express) for high-speed data transfer. It has three channels, each having one 3Gb Xilinx RocketIO transceiver and one SFP for either an electrical RJ45 1GbE (1000 Base-T) ethernet adapter or an optical LC.

Four additional RocketIO transceivers connect to an internal 40-pin connector. Two quad-frequency oscillators allow eight different clock speeds.

EDT provides FPGA configuration files so you can output and acquire data using 8b/10b encoding. Custom configuration files can be requested.

The main board supplies high-speed DMA, plus additional memory and programmable FPGA resources.

Applications

High-bandwidth optical link Ethernet monitoring Fast serial interfaces for cameras and other devices

Specificatio	ons				
Product Type	3x3G is a 3-channel mezzanine board for up to 3 Gb/s serial data or 1GbE per channel; it requires a main board.				
FPGA Resources	One programmable FPGA (Xilinx Virtex II Pro XC2VP7 or optional 30), plus FPGA resources on main board				
Memory	SRAM DRAM (DDR)		0 O or optional 512 MB or 2 GB; 2 GB is needed for snapshot recording at rates of 1.8 Gb/s or faster with PCI SS or PCI GS main board		
Clocks	106.25, 124, 125, or 152.25 MHz; custom frequencies are possible				
Data Rates	Data rates are dependent on data format and main board.				
Data Format (I/O)	Channels 0, 1, and 2		Each channel supports 1GbE (electrical or optical) or serial data up to 3 Gb/s with 8b/10b encoding (other encoding options may be available upon request)		
Transceivers	Up to three optional SFPs (one per channel) are available, each supporting the data formats and specifications shown below.				
	CHANNELS 0, 1, 2 Electrical: 1GbE		Optical: 1GbE or serial data up to 3 Gb/s		
	(SFPs)	(1000 Base-T)	850 nm	1310 nm	
	Output power	-	-9 to -2.5 dBm	-9.5 to -3 dBm	
	Center wavelength	-	830 to 860 nm	1270 to 1360 nm	
	Sensitivity	-	-18 dBm	-18 dBm	
	Maximum input power	-	0 dBm	0 dBm	
	Connectors	RJ45	LC	LC	
Connectors	One RJ45 or LC on each transceiver as shown above One 40-pin Q-strip socket				
Cabling	Consult EDT for purchase options.				
Physical	Weight		6.8 oz. typical (with all three SFPs)		
	Dimensions		6.6 x 4.2 x 0.5 in. (with	6.6 x 4.2 x 0.5 in. (with a main board)	
Environmental	Temperature		Operating 0° to 40° C	Operating 0° to 40° C	
			Non-operating -40° to	Non-operating -40° to 70° C	
	Humidity		Operating 1% to 90%,	Operating 1% to 90%, non-condensing at 40° C	
	Non-operating 95%, non-condensing at 45° C				
System and Software	For details on system requirements and EDT-provided software driver packages, see specifications for your EDT main board.				

Support

EDT offers engineer-to-engineer customer support, from phone consultation to custom design of hardware, firmware, and software. Contact us for options and details.

Contact

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Ordering Options

- Main board: PCI SS / PCI GS / PCIe8 LX
- FPGA: XC2VP**7** / 30
- DRAM: **0** / 512 MB / 2 GB
- Transceivers: Up to 3 SFPs (one per channel, each electrical or optical; options above)

Bold is default. For more options, see main board datasheet. **Ask about custom options.**